JUL 2 5 2006 W

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wu et al.

Attorney Docket No.: NOVLP091

Application No.: 10/820,525

Examiner: Not Yet Assigned

Filed: April 7, 2004

Group: 2812

Title: METHODS FOR PRODUCING LOW-K CDO FILMS WITH LOW RESIDUAL STRESS

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on July 21, 2006 in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents,

P.O. Box 1450, Alexandria, VA 22313-1450.

Signed:

Tara Hayden

INFORMATION DISCLOSURE STATEMENT 37 CFR §§1.56 AND 1.97(b)

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP091).

Respectfully submitted,

BEYER WEAVER & THOMAS, LLP

P.O. Box 70250 Oakland, CA 94612-0250 Denise S. Bergin

Registration No. 50,581

JUL 2 5 7006

Form 1449 (Modified)

Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Atty Docket No. Application No.:
NOVLP091
10/820,525

Applicant:
Wu et al.
Filing Date
04-07-2004
2812

U.S. Patent Documents

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	A1	6,867,086 B1	03.2005	Chen et al.			
	A2	6,903,004	06.2005	Spencer et al.			
	A3	6,232,658 B1	05.2001	Catabay et al.			
	A4	6,171,661	01.2001	Zheng et al.			
	A5	2002/0016085	02.2002	Huang et al.			
	A6	6,455,417	09.2002	Bao et al.			
	A7	7,018,918	03.2006	Kloster et al.			
	A8	6,849,549	02.2005	Chiou et al.			
	A9	2002/0141024 A1	10.2002	Retschke et al.			
	A10	2002/0064341 A1	05.2002	Fauver et al.			
						<u> </u>	
	l						

## **Other Documents**

Examiner	Ì					
Initial	No.					
	C1	U.S. Office Action mailed May 31, 2006, from U.S Application No. 10/941,502 [Atty				
		Dkt No. NOVLP107/NVLS-2932].				
	C2	U.S. Office Action mailed May 30, 2006, from U.S Application No. 10/785,235 [Atty				
		Dkt No. NOVLP085/NVLS-2875].				
	C3	U.S. Office Action mailed May 31, 2006, from U.S Application No. 10/849,568 [Atty				
	1	Dkt No. NOVLP083/NVLS-2867].				
	C4 U.S. Office Action mailed May 2, 2006, from U.S Application No. 11/05					
	Dkt No. NOVLP100/NVLS-2956].					
	C5	U.S. Office Action mailed June 15, 2006, from U.S Application No. 10/800,409 [Atty				
		Dkt No. NOVLP098/NVLS-2907].				
	C6 Kelman et al., "Method for Reducing Stress in Porous Dielectric Films", U.S.					
		Application No. 11/369,311, filed March 6, 2006 (Atty Dkt: NOVLP154/NVLS-				
		3121)				
	C7	U.S. Office Action mailed June 28, 2006, from U.S Application No. 10/825,88				
	C8					
	C9					
	C10					
	Dkt No. NOVLP094/NVLS-2919].					
Examiner	•	Date Considered				

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.